

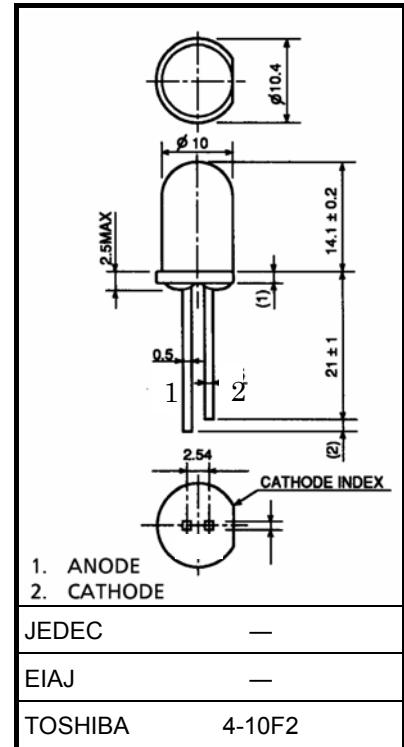
TOSHIBA LED Lamp InGaAlP Red Light Emission

# TLRH190P(F)

## Panel Circuit Indicator

- Lead(Pb)-free products (lead: Sn-Ag-Cu)
- 10 mm package
- InGaAlP technology
- All plastic mold type.
- Colorless clear lens
- Low drive current, high intensity red light emission  
Recommended forward current:  $I_F = 1\sim 20\text{mA (DC)}$
- All plastic molded lens, provides an excellent on-off contrast ratio.
- Fast response time, capable of pulse operation.
- High power luminous intensity
- Without stand-offs
- Applications: Suitable for outdoor message signboard, safety equipment.

Unit in mm



Weight: 1.0 g

## Maximum Ratings (Ta = 25°C)

Characteristic	Symbol	Rating	Unit
Forward current (DC)	$I_F$	50	mA
Reverse voltage	$V_R$	4	V
Power dissipation	$P_D$	125	mW
Operating temperature range	$T_{opr}$	-30~85	°C
Storage temperature range	$T_{stg}$	-40~120	°C

## Electrical And Optical Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Forward voltage	$V_F$	$I_F = 20\text{ mA}$	—	1.9	2.5	V
Reverse current	$I_R$	$V_R = 4\text{ V}$	—	—	50	μA
Luminous intensity	TLRH190P(F)	$I_F = 20\text{ mA}$ (Note)	4760	19000	—	mcd
	TLRH190P (WX,F)		8500	—	41400	
Peak emission wavelength	$\lambda_P$	$I_F = 20\text{ mA}$	—	(644)	—	nm
Spectral line half width	$\Delta\lambda$	$I_F = 20\text{ mA}$	—	18	—	nm
Dominant wavelength	$\lambda_d$	$I_F = 20\text{ mA}$	—	630	—	nm

(Note): Lamps are classified into the following ranks according to their luminous intensity, and packed in boxes by each rank.

V: 4760 - 12900mcd, W: 8500 - 23000mcd, X: 15300mcd -

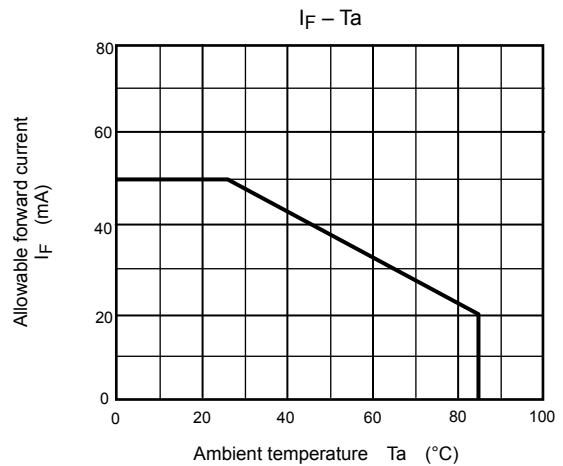
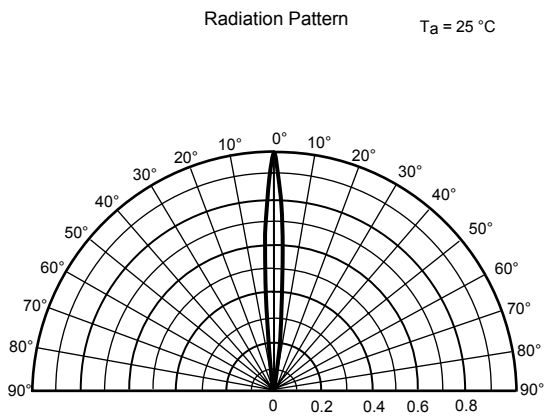
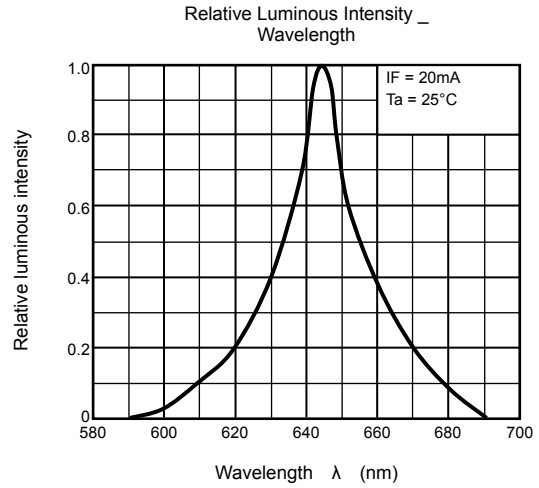
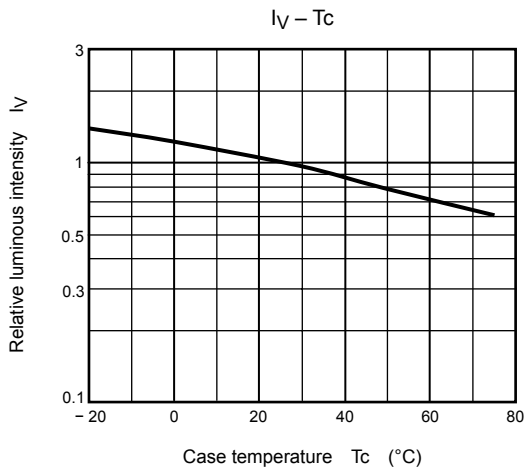
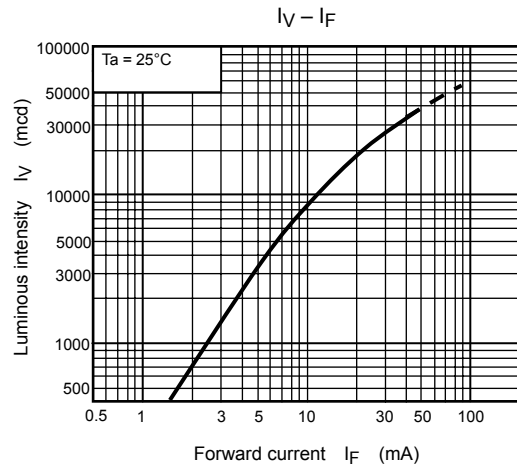
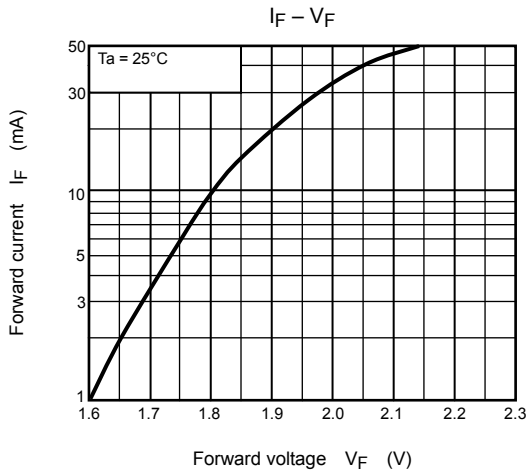


For part availability and ordering information please call Toll Free: 800.984.5337  
Website: [www.marktechopto.com](http://www.marktechopto.com) | Email: [info@marktechopto.com](mailto:info@marktechopto.com)

**Precaution**

Please be careful of the followings

- Soldering temperature: 260°C max                      Soldering time: 3 s max  
(Soldering portion of lead: up to 1.6 mm from the body of the device)
- If the lead is formed, the lead should be formed up to 1.6 mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.
- This visible LED lamp also emits some IR light. If a photodetector is located near the LED lamp, please ensure that it will not be affected by this IR light.



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